

Material Declaration Sheet

- Device : ASFC64G31T5B-51BIN / ASFC64G31T5B-51BAN
- Package : 11.5 x 13.0mm 153b FBGA eMMC
- Weight (mg) : 319.93781mg

product-component	mass (pcs.)	material unit mass (mg)	material name (e.g. Substrate)	substance name (e.g. Copper)	CAS No. (e.g. 7440-50-8)	substance mass (mg)	or substance concentration (%)
Printed Circuit Board	1	89.67721	Au	Au Plating	7440-57-5	0.18056	0.20
			Ni	Ni Plating	7440-02-0	1.40425	1.57
			Cu	Cu Plating	7440-50-8	60.24576	67.18
			Core	Copper foil	7440-50-8	9.65396	10.77
				E-Glass Fabric	65997-17-3	9.65396	10.77
			Solder Mask	Poly(acrylicacid)	Trade Secret	3.48708	3.89
				Barium sulfate	7727-43-7	2.09543	2.34
				3-Methoxy-3-methylbutyl Acetate	103429-90-9	1.02391	1.14
				Dipropylene Glycol Monomethyl Ether	34590-94-8	0.86607	0.97
				Talc	14807-96-6	0.21284	0.24
				Photopolymerization	Trade Secret	0.21284	0.24
				Solvent naphtha	64742-94-5	0.21284	0.24
				Auxiliaries	Trade Secret	0.21284	0.24
				Silicon dioxide	Trade Secret	0.04121	0.05
				Phthalocyanine blue	Trade Secret	0.04121	0.05
				Organic pigment	Trade Secret	0.13243	0.15
material unit mass (mg)	89.67721						
Chip Capacitor	2	1.60000	Ceramics	witherite	1304-28-5	0.63900	39.94
				Titanium dioxide	13463-67-7	0.31950	19.97
				Misc	Blank	0.10650	6.66
			Outer electrode	Copper	7440-50-8	0.17190	10.74
				Borosilicate Glass	-	0.00382	0.24
				Silicon dioxide	7631-86-9	0.01528	0.96
			Nickel plating	Nickel	7440-02-0	0.01800	1.13
			Inner electrode	Nickel	7440-02-0	0.27900	17.44
			Tin plating	Tin	7440-31-5	0.04700	2.94
material unit mass (mg)	3.20000						
FLASH Die	1	11.87000	Silicon Die	Silicon	7440-21-3	11.86999	99.9999
				Misc	-	0.00001	0.0001
material unit mass (mg)	11.87000						
FLASH Die Attach - DAF Tape	1	0.20000	Adhesive Resin	Acryl copolymer	Trade Secret	0.08571	42.86
				Epoxy	29690-82-2	0.02857	14.29
				Hardener	Trade Secret	0.02857	14.29
				Silica	7631-86-9	0.05714	28.57
material unit mass (mg)	0.20000						
Controller Die	1	2.64060	Silicon Die	Silicon	7440-21-3	2.64060	99.9999

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	1	2.64060	Silicon Die	Misc	-	0.00000	0.0001
material unit mass (mg)	2.64060						
Controller Die Attach - Adhesive	1	0.10000	Adhesive	EP	-	0.04896	48.96
				Silanamin, 1,1,1-Trimethyl-N-(trimethylsilyl)-, Hydrolyseprodukte mit Siliciumdioxid	68909-20-6	0.03400	34.00
				Siliziumdioxid	7631-86-9	0.01700	17.00
				Dieisentrioxid	1309-37-1	0.00003	0.03
				Calciumbis[4-[[3-[[2-hydroxy-3-[[4-methoxyphenyl]amino]carbonyl]-1-naphthyl]azo]-4-methylbenzoyl]amino]benzolsulfonat]	43035-18-3	0.00001	0.01
				N-(2,3-Dihydro-2-oxo-1Hbenzimidazol-5-yl)-3-hydroxy-4-[[2-methoxy-5-methyl-4-[(methylamino)sulfonyl]phenyl]azo]naphthalin-2-carboxamid	51920-12-8	0.00001	0.01
material unit mass (mg)	0.10000						
Bonding Wire	1	0.41000	Bonding wire	Gold	7440-57-5	0.40996	99.99
				Misc	-	0.00004	0.01
material unit mass (mg)	0.41000						
Molding Compound	1	195.00000	Molding Compound	Silica (Fused)	60676-86-0 7631-86-9	169.06500	86.70
				Epoxy resin (1)	-	9.75000	5.00
				Epoxy resin (2)	-	4.87500	2.50
				Phenol resin (1)	-	5.85000	3.00
				Phenol resin (2)	-	4.87500	2.50
				Carbon black	1333-86-4	0.58500	0.30
material unit mass (mg)	195.00000						
Solderpaste	1	0.01000	Solderpaste	Tin	7440-31-5	0.00800	80.00
				Silver	7440-22-4	0.00040	4.00
				Rosin, oligomers	65997-05-9	0.00060	6.00
				2-(2-Hexyloxyethoxy)ethanol	112-59-4	0.00060	6.00
				Indium	7440-74-6	0.00036	3.60
				Bismut	7440-69-9	0.00004	0.40
material unit mass (mg)	0.01000						
Solder Balls	153	0.11000	Solder Balls	Tin	7440-31-5	0.10604	96.40
				Silver	7440-22-4	0.00330	3.00
				Copper	7440-50-8	0.00066	0.60
material unit mass (mg)	16.83000						
	319.93781						